



## **OKI Semiconductor**

# **FEDR27V1652L-02-01** Issue Date: Jun. 16, 2005

## MR27V1652L

 $1 \text{M-Word} \times 16 \text{-Bit or } 2 \text{M-Word} \times 8 \text{-Bit Page Mode } P2ROM$ 

#### **FEATURES**

- $\cdot$  1,048,576-word  $\times$  16-bit / 2,097,152-word  $\times$  8-bit electrically switchable configuration
- · Page size of 8-word x 16-Bit or 16-word x 8-Bit
- · 3.0 V to 3.6 V power supply
- ·Random Access time 100 ns MAX ·Page Access time 30 ns MAX
- · Operating current 60 mA MAX (5MHz)
- · Standby current 10 µA MAX
- · Input/Output TTL compatible
- · Three-state output

#### **PACKAGES**

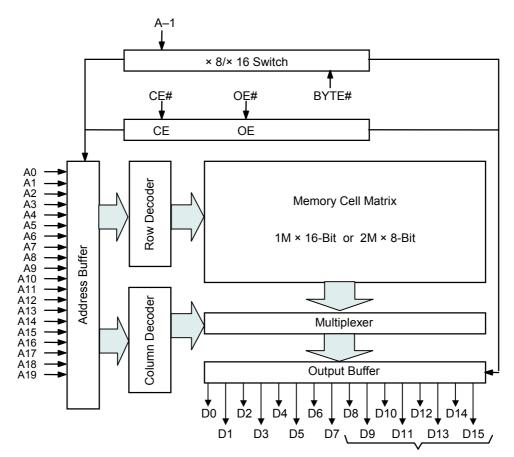
· MR27V1652L-xxxMA 44-pin plastic SOP (SOP44-P-600-1.27-K)

#### P2ROM ADVANCED TECHNOLOGY

P2ROM stands for Production Programmed ROM. This exclusive Oki technology utilizes factory test equipment for programming the customers code into the P2ROM prior to final production testing. Advancements in this technology allows production costs to be equivalent to MASKROM and has many advantages and added benefits over the other non-volatile technologies, which include the following;

- PIN CONFIGURATION (TOP VIEW) 2 43 A19 A18 A17 42 A8 4 Α7 41 A9 A6 5 40 A10 6 7 A5 39 A11 38 A12 A4 АЗ 8 37 A13 A2 9 36 A14 Α1 35 A15 A0 11 34 A16 12 33 BYTE# CE#  $V_{\text{SS}} \\$ 32 V<sub>SS</sub> 31 D15/A-1 OE# 14 D0 15 30 D7 D8 16 29 D14 17 28 D6 27 D13 D1 D9 18 D2 19 26 D5 20 25 D12 D10 D3 21 24 D4 23 V<sub>CC</sub> D11 22 44SOP
- Short lead time, since the P2ROM is programmed at the final stage of the production process, a large P2ROM inventory "bank system" of un-programmed packaged products are maintained to provide an aggressive lead-time and minimize liability as a custom product.
- No mask charge, since P2ROMs do not utilize a custom mask for storing customer code, no mask charges apply
- No additional programming charge, unlike Flash and OTP that require additional programming and handling costs, the P2ROM already has the code loaded at the factory with minimal effect on the production throughput. The cost is included in the unit price.
- Custom Marking is available at no additional charge.
- Pin Compatible with Mask ROM and some FLASH products.

#### **BLOCK DIAGRAM**



In 8-bit output mode, these pins are placed in a high-Z state and pin D15 functions as the A-1 address pin.

#### **PIN DESCRIPTIONS**

Pin name	Functions			
D15 / A-1	Data output / Address input			
A0 to A19	Address inputs			
D0 to D14	Data outputs			
CE#	Chip enable input			
OE#	Output enable input			
BYTE#	Word / Byte select input			
Vcc	Power supply voltage			
$V_{SS}$	Ground			
NC	No connect			

#### **FUNCTION TABLE**

Mode	CE#	OE#	BYTE#	Vcc	D0 to D7	D8 to D14	D15/A-1
Read (16-Bit)	L	L	Н			D <sub>OUT</sub>	
Read (8-Bit)	L	L	L		D <sub>OUT</sub>	Hi–Z	L/H
Outrot disable		Н	Н	0.01/		<b>⊔</b> ; 7	
Output disable	_	П	L	3.3 V	Hi–Z		*
Ctondhu	H *		Н		Hi–Z		
Standby		ボ	L				*

<sup>\*:</sup> Don't Care (H or L)

#### **ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Condition	Value	Unit
Operating temperature under bias	Та		0 to 70	°C
Storage temperature	Tstg	_	-55 to 125	°C
Input voltage	Vı		-0.5 to V <sub>CC</sub> +0.5	V
Output voltage	Vo	relative to V <sub>SS</sub>	-0.5 to V <sub>CC</sub> +0.5	V
Power supply voltage	V <sub>CC</sub>		-0.5 to 5	V
Power dissipation per package	P <sub>D</sub>	Ta = 25°C	1.0	W
Output short circuit current	los	_	10	mA

#### RECOMMENDED OPERATING CONDITIONS

 $(Ta = 0 \text{ to } 70^{\circ}C)$ 

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
V <sub>CC</sub> power supply voltage	V <sub>CC</sub>		3.0	_	3.6	V
Input "H" level	V <sub>IH</sub>	$V_{CC}$ = 3.0 to 3.6 V	2.2	_	V <sub>CC</sub> +0.5*	V
Input "L" level	V <sub>IL</sub>		-0.5**	_	0.6	V

#### Voltage is relative to $V_{\text{SS}}$ .

\* : Vcc+1.5V(Max.) when pulse width of overshoot is less than 10ns.

#### PIN CAPACITANCE

 $(V_{CC} = 3.3 \text{ V}, \text{ Ta} = 25^{\circ}\text{C}, \text{ f} = 1 \text{ MHz})$ 

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Input	C <sub>IN1</sub>	V <sub>1</sub> = 0 V	_	_	10	
BYTE#	C <sub>IN2</sub>	V <sub>1</sub> – U V	_	_	120	pF
Output	C <sub>OUT</sub>	V <sub>O</sub> = 0 V	_	_	10	

<sup>\*\*</sup>: -1.5V(Min.) when pulse width of undershoot is less than 10ns.

#### **ELECTRICAL CHARACTERISTICS**

#### **DC** Characteristics

 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}, \text{ Ta} = 0 \text{ to } 70^{\circ}\text{C})$ 

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Input leakage current	ILI	$V_I = 0$ to $V_{CC}$	_	_	10	μΑ
Output leakage current	I <sub>LO</sub>	$V_O = 0$ to $V_{CC}$	_	_	10	μΑ
V <sub>CC</sub> power supply current	I <sub>ccsc</sub>	CE# = V <sub>CC</sub>	_	_	10	μΑ
(Standby)	I <sub>CCST</sub>	CE# = V <sub>IH</sub>	_	_	1	mA
V <sub>CC</sub> power supply current	1	CE#= V <sub>IL</sub> , OE# = V <sub>IH</sub> ,			60	mA
(Read)	I <sub>CCA</sub>	f = 5MHz	_	_	00	IIIA
Input "H" level	V <sub>IH</sub>	_	2.2	_	V <sub>CC</sub> +0.5*	V
Input "L" level	V <sub>IL</sub>		-0.5**	_	0.6	V
Output "H" level	V <sub>OH</sub>	I <sub>OH</sub> = -1 mA	2.4	_	_	V
Output "L" level	V <sub>OL</sub>	$I_{OL} = 2 \text{ mA}$	_	_	0.4	V

#### Voltage is relative to V<sub>SS</sub>.

- \* : Vcc+1.5V(Max.) when pulse width of overshoot is less than 10ns.
- \*\*: -1.5V(Min.) when pulse width of undershoot is less than 10ns.

#### **AC Characteristics**

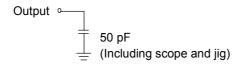
 $(V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}, \text{ Ta} = 0 \text{ to } 70^{\circ}\text{C})$ 

Parameter	Symbol	Condition	Min.	Max.	Unit
Address cycle time	tc		100		ns
Address access time	t <sub>ACC</sub>	CE# = OE# = V <sub>IL</sub>		100	ns
Page cycle time	t <sub>PC</sub>		30		ns
Page access time	t <sub>PAC</sub>	_	_	30	ns
CE# access time	t <sub>CE</sub>	OE# = V <sub>IL</sub>		100	ns
OE# access time	t <sub>OE</sub>	CE# = V <sub>IL</sub>		30	ns
Output disable time	t <sub>CHZ</sub>	OE# = V <sub>IL</sub>	0	20	ns
Output disable time	t <sub>OHZ</sub>	CE# = V <sub>IL</sub>	0	20	ns
Output hold time	tон	CE# = OE# = V <sub>IL</sub>	0	_	ns

#### Measurement conditions

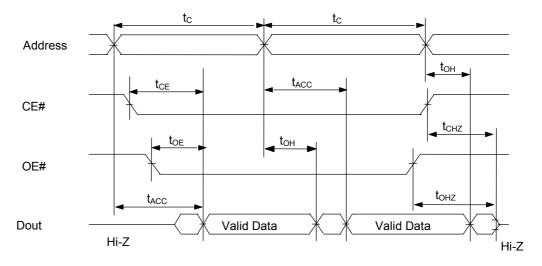
Input signal level ------0 V/3 V Input timing reference level------1/2Vcc Output load ------50 pF Output timing reference level ------1/2Vcc

#### Output load

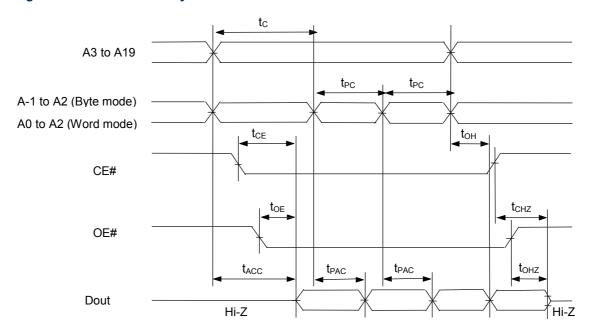


## TIMING CHART (READ CYCLE)

#### **Random Access Mode Read Cycle**

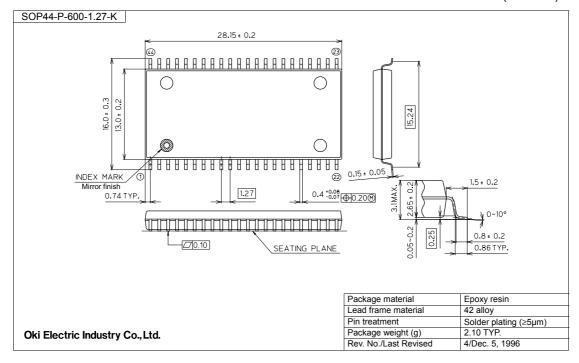


### Page Access Mode Read Cycle



#### **PACKAGE DIMENSIONS**

(Unit: mm)



Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage.

Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

### **REVISION HISTORY**

Document		Page			
No.	Date	Previous Edition	Current Edition	Description	
FEDR27V1652L-02-01	Jun. 16, 2005	-	_	Final edition 1	

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